

L Number	Hits	Search Text	DB	Time stamp
73	5	("4786954" "4972248" "5286671" "5298767" "5666833").PN.	USPAT	2004/10/13 09:54
74	11	5401672.URPN.	USPAT	2004/10/13 09:55
75	2	("5492863" "6051450").PN.	USPAT	2004/10/13 09:56
76	3	6238951.URPN.	USPAT	2004/10/13 09:57
77	9	("4769344" "5296408" "5317922" "5335550" "5430421" "5602385" "5610431" "5929728" "6124145").PN.	USPAT	2004/10/13 09:57
78	2	("5578869" "5610431").PN.	USPAT	2004/10/13 09:58
79	1	"5740606".PN.	USPAT	2004/10/13 09:59
182	8	("4689113" "5241450" "5366906" "5419806" "5880010" "6255726" "6355501" "6355976").PN.	USPAT	2004/10/13 10:05
183	30	(die or wafer or substrate) near3 (edge or periphery or peripheral or outer or outside) near10 (crack or cracking or cracked or corrsion or corroding or corroded or contamination or contaminating) near10 (dice or dicing or singulation or singulating or cleaving or cleavage or cleave or scribe or scribing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/13 10:23
184	346	(wafer or substrate) near3 (edge or periphery or peripheral or outer or outside) near6 (ring or barrier or wall or spacer) near4 (metal or metallic or solder or tin or copper or cu or gold or au)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/13 10:24
185	241	(wafer or substrate) near3 (edge or periphery or peripheral or outer or outside) near6 (ring or wall or spacer) near4 (metal or metallic or solder or tin or copper or cu or gold or au)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/13 10:24
186	267	(wafer or substrate) near3 (edge or periphery or peripheral or outer or outside) near6 (ring or wall or spacer or ridge or grid) near4 (metal or metallic or solder or tin or copper or cu or gold or au)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/13 10:38
187	71	(wafer or substrate) near3 (edge or periphery or peripheral or outer or outside) near6 (seal) near4 (metal or metallic or solder or tin or copper or cu or gold or au)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/13 10:41
188	269	(wafer or substrate) near3 (edge or periphery or peripheral or outer or outside) near6 (seal\$3) near4 (hermetic\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/13 10:42
-	135	((die or wafer or chip) near2 (bond or bonding or attachment or attaching or bonded or attached) or flip adj chip) and (barrier or corrosion or contamination or crack or sealing or seal) near3 (edge or periphery or peripheral or outside or outer) near3 (metal or copper or cu or metallic or aluminum or gold or silver)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/13 10:07
-	8	("4689113" "5241450" "5366906" "5419806" "5880010" "6255726" "6355501" "6355976").PN.	USPAT	2004/07/26 16:04
-	1173	((die or wafer or chip or substrate) near2 (bond or bonding or attachment or attaching or bonded or attached) or flip adj chip) and (barrier or seal or sealing) near3 (edge or periphery or peripheral or outside or outer) near3 (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 10:39

-	47	((die or wafer or chip or substrate) near2 (bond or bonding or attachment or attaching or bonded or attached) or flip adj chip) and (barrier or seal or sealing) near3 (edge or periphery or peripheral or outside or outer) near3 (wafer or substrate) near15 (metal or metallic or copper or cu or gold or au or silver or ag or nickel or ni or aluminum or al)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 10:52
-	107	((die or wafer or chip or substrate) near2 (bond or bonding or attachment or attaching or bonded or attached) or flip adj chip) and (edge or periphery or peripheral or outside or outer) near3 (raised or elevated or projection or ridge) near10 (metal or metallic or aluminum or al or copper or cu or gold or au or silver or ag or nickel or ni)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 11:09
-	4108	((die or wafer or chip) near2 (bond or bonding or attachment or attaching or bonded or attached) or flip adj chip) and (seal or sealing or sealed) near2 (hermetic\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 13:03
-	709	((die or wafer or chip) near2 (bond or bonding or attachment or attaching or bonded or attached) or flip adj chip) and (seal or sealing or sealed) near2 (hermetic\$5) near10 (metal or metallic or copper or cu or gold or au or nickel or ni or platinum or pt)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 13:08
-	340	(wafer near2 (bond or bonding or attachment or attaching or bonded or attached) or flip adj chip) and (seal or sealing or sealed) near2 (hermetic\$5) near10 (metal or metallic or copper or cu or gold or au or nickel or ni or platinum or pt)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 13:49
-	287	flip adj chip same (seal or sealing or sealed) near2 (hermetic\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/06 13:50
-	17	(US-6306526-\$ or US-6596117-\$ or US-5241450-\$ or US-6697257-\$ or US-6566745-\$ or US-6518096-\$ or US-6373130-\$ or US-6643920-\$).did. or (US-20040014308-\$ or US-20010022207-\$ or US-20040104460-\$ or US-20040066258-\$ or US-20040016995-\$ or US-20040011783-\$ or US-20020113296-\$ or US-20020090754-\$ or US-20030000067-\$).did.	USPAT; US-PGPUB	2004/10/06 14:49
-	107	438/107.ccls. and (barrier or seal or sealing or pillar or line or spacer) near5 (periphery or peripheral or perimeter or edge or outer or outside)	USPAT; US-PGPUB	2004/10/06 15:20
-	1	6661085.pn.	USPAT; US-PGPUB	2004/10/06 14:52
-	8	("4689113" "5241450" "5366906" "5419806" "5880010" "6255726" "6355501" "6355976").PN.	USPAT	2004/10/06 14:52
-	140	438/107.ccls. and (barrier or seal or sealing or pillar or line or spacer) near5 (periphery or peripheral or perimeter or edge or outer or outside)	USPAT; US-PGPUB	2004/10/12 11:04
-	73	438/107.ccls. and (hermetic\$5 or peripheral or edge) near2 (seal\$3)	USPAT; US-PGPUB	2004/10/12 10:50
-	76	438/108.ccls. and (hermetic\$5 or peripheral or edge) near2 (seal\$3)	USPAT; US-PGPUB	2004/10/12 10:50
-	182	438/108.ccls. and (barrier or seal or sealing or pillar or line or spacer or sealed) near5 (periphery or peripheral or perimeter or edge or outer or outside or hermetic\$5)	USPAT; US-PGPUB	2004/10/12 11:37

-	51	438/456.ccls. and (barrier or seal or sealing or pillar or line or spacer or sealed) near5 (periphery or peripheral or perimeter or edge or outer or outside or hermetic\$5)	USPAT; US-PGPUB	2004/10/12 11:48
-	74	438/458.ccls. and (barrier or seal or sealing or pillar or line or spacer or sealed) near5 (periphery or peripheral or perimeter or edge or outer or outside or hermetic\$5)	USPAT; US-PGPUB	2004/10/12 12:00
-	126	438/460.ccls. and (barrier or seal or sealing or pillar or line or spacer or sealed) near5 (periphery or peripheral or perimeter or edge or outer or outside or hermetic\$5)	USPAT; US-PGPUB	2004/10/12 12:11
-	144	438/462.ccls. and (barrier or seal or sealing or pillar or line or spacer or sealed) near5 (periphery or peripheral or perimeter or edge or outer or outside or hermetic\$5)	USPAT; US-PGPUB	2004/10/12 12:18
-	1305	(scribe or scribing or cleave or cleaving or singulating or singulation or dice or dicing) near5 (barrier or seal or sealed or sealing)	USPAT; US-PGPUB	2004/10/12 12:19
-	82	(scribe or scribing or cleave or cleaving or singulating or singulation or dice or dicing) near8 (barrier or seal or sealed or sealing) near4 (hermetic\$5)	USPAT; US-PGPUB	2004/10/12 12:20
-	27	(US-6596117-\$ or US-6373130-\$ or US-6306526-\$ or US-5241450-\$ or US-6697257-\$ or US-6566745-\$ or US-6518096-\$ or US-5262351-\$ or US-6643920-\$ or US-6649444-\$ or US-6479320-\$ or US-6455353-\$ or US-6238951-\$ or US-6297072-\$ or US-5401672-\$ or US-6461893-\$).did. or (US-20040014308-\$ or US-20010022207-\$ or US-20040104460-\$ or US-20040066258-\$ or US-20040016995-\$ or US-20040011783-\$ or US-20020113296-\$ or US-20030000067-\$ or US-20020119597-\$ or US-20020106867-\$ or US-20010055856-\$).did.	USPAT; US-PGPUB	2004/10/12 14:09
-	571	(wafer or substrate or chip or device) near3 (edge or periphery or peripheral or scribe or scribing or singulation or singulating or cleave or cleavage or cleaving or dicing) near8 (seal or sealing or guard or barrier or wall or spacer) near3 ring\$2	USPAT; US-PGPUB	2004/10/12 14:10
-	653	(wafer or substrate or chip or device) near3 (edge or periphery or peripheral or scribe or scribing or singulation or singulating or cleave or cleavage or cleaving or dicing) near8 (seal or sealing or guard or barrier or wall or spacer) near3 ring\$2	USPAT; US-PGPUB	2004/10/12 14:11
-	426	(wafer or substrate or chip or device) near3 (edge or periphery or peripheral or scribe or scribing or singulation or singulating or cleave or cleavage or cleaving or dicing) near5 (seal or sealing or guard or barrier or wall or spacer) near2 ring\$2	USPAT; US-PGPUB	2004/10/12 14:12
-	6959	(wafer or substrate) near2 (periphery or edge or peripheral or outer) near6 (barrier or spacer or ring or seal or sealing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/12 17:12
-	1654	(wafer or substrate) near2 (periphery or edge or peripheral or outer) near6 (barrier or spacer or ring or seal or sealing) and (wafer or substrate) near3 (stack or stacked or stacking or bonding or bonded or bond or 3d or "3-d" or three near dimensional)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/12 17:13

-	210	(wafer or substrate) near (periphery or edge or peripheral or outer) near4 (barrier or spacer or ring or seal or sealing) same (wafer or substrate) near3 (stack or stacked or stacking or bonding or bonded or bond or 3d or "3-d" or three near dimensional)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/12 17:13
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